



FF1136 - PbSn SOLDER BALLS  
FFG1136 - SnAgCu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.85	<i>~</i>	3.25	2
A <sub>1</sub>	0.40	0.50	0.60	
A <sub>2</sub>	0.90	<i>~</i>	1.40	
D/E	35.00 BASIC			
D <sub>1</sub> /E <sub>1</sub>	33.00 REF			
e	1.00 BASIC			
Øb	0.50	0.60	0.70	
aaa	<i>~</i>	<i>~</i>	0.20	
ccc	<i>~</i>	<i>~</i>	0.35	
ddd	<i>~</i>	<i>~</i>	0.30	
eee	<i>~</i>	<i>~</i>	0.10	
M	34			

**NOTES:**

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. CONFORMS TO JEDEC MS-034-AAR-1 (DEPOPULATED)

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/22/07	1.0	Initial Xilinx release.
08/05/09	1.1	Changed the overall package thickness (symbol A) from 2.70 min – 3.40 max to 2.85 min – 3.25 max.

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